STGIPQ3H60T-HL
STGIPQ3H60T-HZ

SLLIMM™ nano - 2nd series
IPM, 3 A, 600 V, 3-phase IGBT inverter bridge

Datasheet - production data

N2DIP-26L type Z

N2DIP-26L type L

Features

- IPM 3 A, 600 V 3-phase IGBT inverter bridge including 3 control ICs for gates driving and freewheeling diodes
- 3.3 V, 5 V and 15 V TTL/CMOS inputs comparators with hysteresis and pull-down/ pull-up resistors
- Internal bootstrap diode
- Optimized for low electromagnetic interference
- Undervoltage lockout
- $V_{CE(SAT)}$ negative temperature coefficient
- Smart shutdown function
- Interlocking function
- Op-amp for advanced current sensing
- Comparator for fault protection against overcurrent
- NTC (UL 1434 CA 2 and 4)
- Isolation rating of 1500 Vrms/min
- Up to ±2 kV ESD protection (HBM C = 100 pF, R = 1.5 kΩ)

Applications

- 3-phase inverters for motor drives
- Home appliances such as dish washer, refrigerator compressors, heating systems, air-conditioning fans, draining and recirculation pumps

Description

This second series of SLLIMM (small low-loss intelligent molded module) nano provides a compact, high performance AC motor drive in a simple, rugged design. It is composed of six improved IGBTs with freewheeling diodes and three half-bridge HVICs for gate driving, providing low electromagnetic interference (EMI) characteristics with optimized switching speed. The package is designed to allow a better and more easily screwed-on heatsink and is optimized for thermal performance and compactness in built-in motor applications or other low power applications where assembly space is limited. This IPM includes a completely uncommitted operational amplifier and a comparator that can be used to design a fast and efficient protection circuit. SLLIMM™ is a trademark of STMicroelectronics.

Table 1. Device summary

Order codes	Marking	Package	Packing
STGIPQ3H60T-HL	GIPQ3H60T-HL	N2DIP-26L type L	Tube
STGIPQ3H60T-HZ	GIPQ3H60T-HZ	N2DIP-26L type Z	Tube

Contents

1 Internal schematic and pin description

Figure 1. Internal schematic diagram and pin configuration

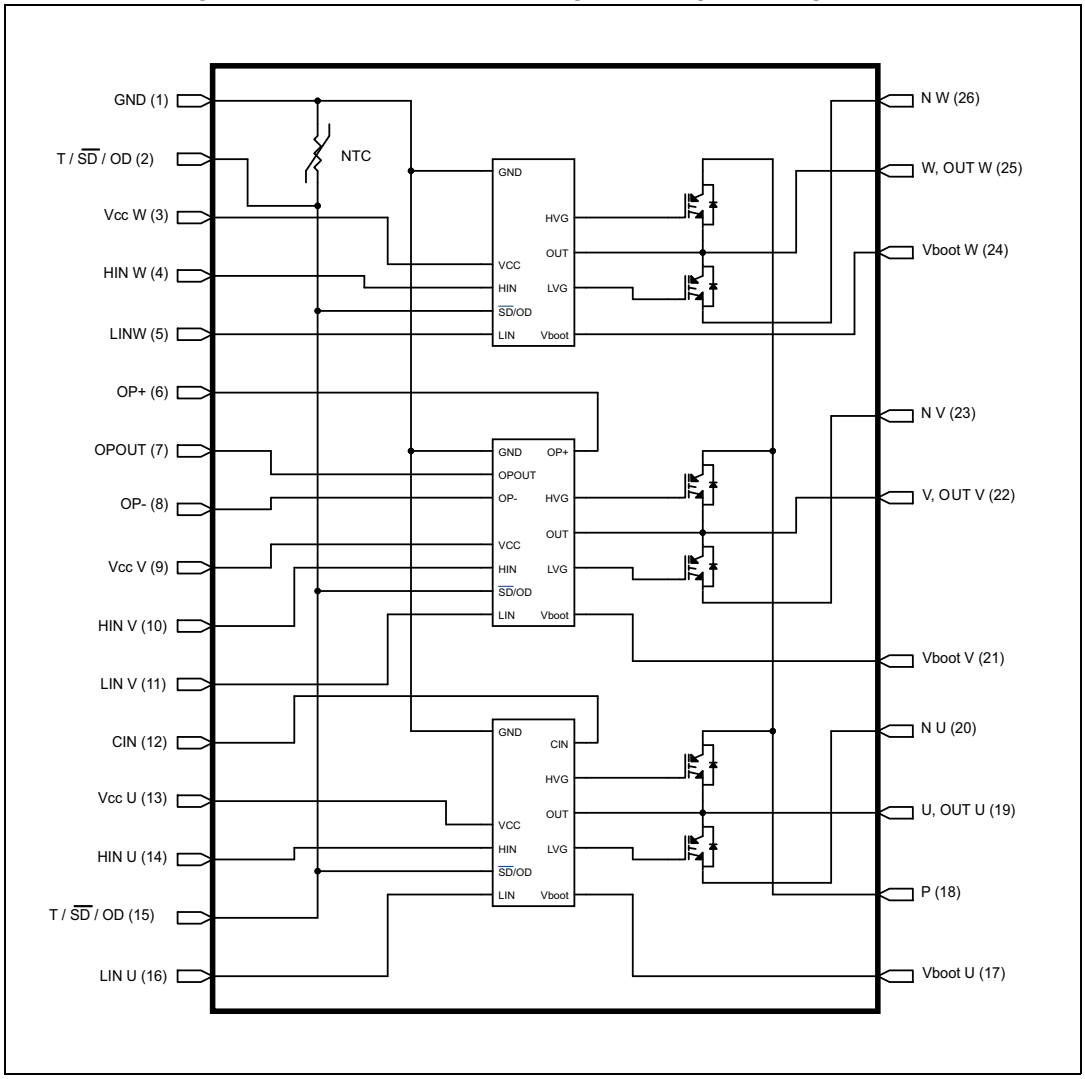


Table 2. Pin description

Pin	Symbol	Description
1	GND	Ground
2	T/$\overline{SD}$/OD	NTC thermistor terminal / shutdown logic input (active low) / open-drain (comparator output)
3	V_{CC} W	Low voltage power supply W phase
4	HIN W	High-side logic input for W phase
5	LIN W	Low-side logic input for W phase
6	OP+	Op-amp non inverting input
7	OPout	Op-amp output
8	OP-	Op-amp inverting input
9	V_{CC} V	Low voltage power supply V phase
10	HIN V	High-side logic input for V phase
11	LIN V	Low-side logic input for V phase
12	CIN	Comparator input
13	V_{CC} U	Low voltage power supply V phase
14	HIN U	High-side logic input for V phase
15	T/$\overline{SD}$/OD	NTC thermistor terminal / shutdown logic input (active low) / open-drain (comparator output)
16	LIN U	Low-side logic input for U phase
17	V_{BOOT} U	Bootstrap voltage for U phase
18	P	Positive DC input
19	U,OUT_U	U phase output
20	N_U	Negative DC input for U phase
21	V_{BOOT} V	Bootstrap voltage for V phase
22	V,OUT_V	V phase output
23	N_V	Negative DC input for V phase
24	V_{BOOT} W	Bootstrap voltage for W phase
25	W,OUT_W	W phase output
26	N_W	Negative DC input for W phase

2 Absolute maximum ratings

(T_j= 25°C unless otherwise noted).

Table 3. Inverter parts

Symbol	Parameter	Value	Unit
V_{CES}	Collector-emitter voltage each IGBT (V_{IN}(1) = 0 V)	600	V
I_C	Continuous collector current each IGBT	3	A
I_{CP}(2)	Peak collector current each IGBT (less than 1ms)	6	A
P_{TOT}	Total dissipation at T_C = 25°C each IGBT	12	W

1. Applied between HINx, LINx and GND for x = U, V, W.
2. Pulsed width limited by max junction temperature.

Table 4. Control parts

Symbol	Parameter	Min	Max	Unit
V_{CC}	Low voltage power supply	-0.3	21	V
V_{BOOT}	Bootstrap voltage	-0.3	620	V
V_{OUT}	Output voltage between OUT_U, OUT_V, OUT_W and GND	V_{BOOT} - 21	V_{BOOT} + 0.3	V
V_{CIN}	Comparator input voltage	-0.3	V_{CC} + 0.3	V
V_{op+}	Op-amp non-inverting input	-0.3	V_{CC} + 0.3	V
V_{op-}	Op-amp inverting input	-0.3	V_{CC} + 0.3	V
V_{IN}	Logic input voltage applied between HINx, LINx and GND	-0.3	15	V
$V_{T/\overline{SD}/OD}$	Open drain voltage	-0.3	15	V
$\Delta V_{OUT/dt}$	Allowed output slew rate		50	V/ns

Table 5. Total system

Symbol	Parameter	Value	Unit
V_{ISO}	Isolation withstand voltage applied between each pin and heat sink plate (AC voltage, t = 60 s)	1500	Vrms
T_J	Power chips operating junction temperature	-40 to 150	°C
T_C	Module case operation temperature	-40 to 125	°C

2.1 Thermal data

Table 6. Thermal data

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Thermal resistance junction-case single IGBT	10	°C/W
	Thermal resistance junction-case single diode	15	
$R_{th(j-a)}$	Thermal resistance junction-ambient	44	

3 Electrical characteristics

(T_j= 25°C unless otherwise noted).

Table 7. Inverter parts

Symbol	Parameter	Test condition	Min	Typ	Max	Unit
I_{CES}	Collector-cut off current (V_{IN}(1) = 0 logic state)	V_{CE} = 550 V, V_{CC} = V_{boot} = 15 V	-		250	µA
$V_{CE(sat)}$	Collector-emitter saturation voltage	V_{CC} = V_{Boot} = 15 V, V_{IN}(1) = 0 to 5 V, I_C = 1 A,	-	2.15	2.6	V
		V_{CC} = V_{Boot} = 15 V, V_{IN}(1) = 0 to 5 V, I_C = 1 A, T_J = 125°C	-	1.65		
V_F	Diode forward voltage	V_{IN}(1) = 0 logic state, I_C = 1 A	-		1.8	V
Inductive load switching time and energy (2)						
t_{on}	Turn-on time	V_{DD} = 300 V, V_{CC} = V_{boot} = 15 V, V_{IN}(1) = 0 to 5 V, I_C = 1 A (see *Figure 3*)	-	275		ns
t_{con}	Cross-over time on		-	90		
t_{off}	Turn-off time		-	890		
t_{coff}	Cross-over time off		-	125		
t_{rr}	Reverse recovery time		-	50		
E_{ON}	Turn-on switching loss		-	18		µJ
E_{OFF}	Turn-off switching loss		-	13		

1. Applied between HINx, LINx and GND for x = U, V, W
2. t_{on} and t_{off} include the propagation delay time of the internal drive. $t_{C(ON)}$ and $t_{C(OFF)}$ are the switching time of IGBT itself under the internally given gate driving condition.

Figure 2. Switching time test circuit

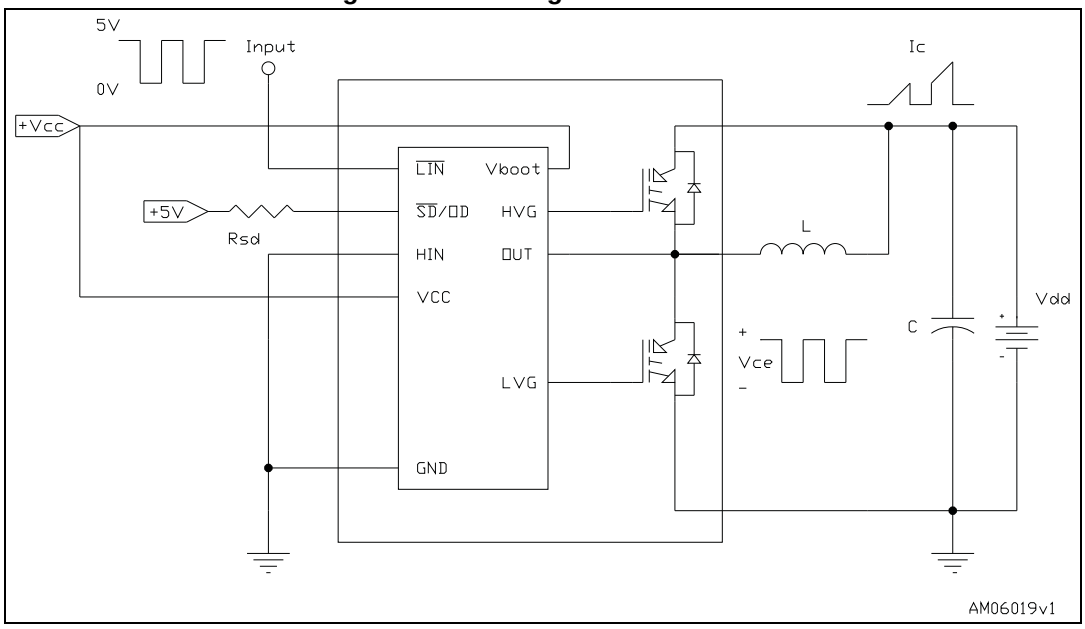
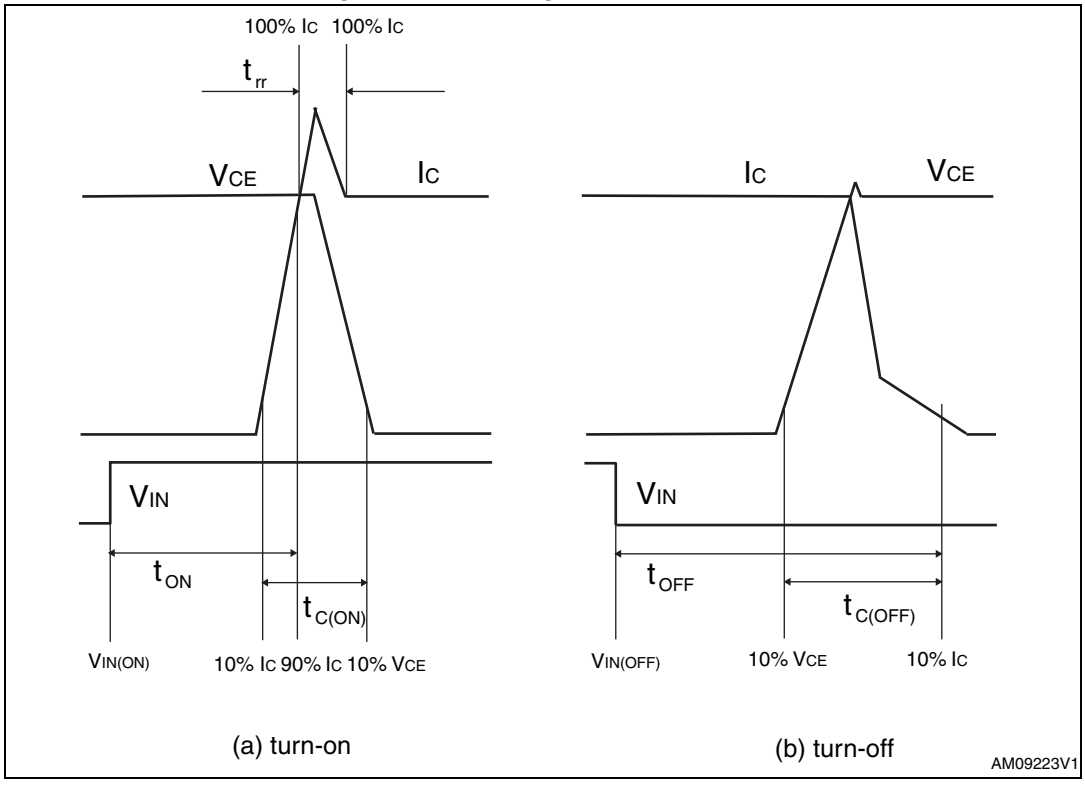


Figure 3. Switching time definition(a)



a. refers to HIN,LIN inputs (active high)

3.1 Control part

(V_{CC}=15 V unless otherwise specified)

Table 8. Low voltage power supply

Symbol	Parameter	Test condition	Min	Typ	Max	Unit
V_{CC_hys}	V_{CC} UV hysteresis		1.2	1.5	1.8	V
$V_{CCH\_th(on)}$	V_{CCH} UV turn-on threshold		11.5	12	12.5	V
$V_{CCH\_th(off)}$	V_{CCH} UV turn-off threshold		10	10.5	11	V
I_{qccu}	Under voltage quiescent supply current	V_{CC} = 10 V; T/$\overline{SD}$/OD = 5V; L_{IN} = H_{IN} = C_{IN} = 0V			150	µA
I_{qcc}	Quiescent current	V_{CC} = 10 V; T/$\overline{SD}$/OD = 5V; L_{IN} = H_{IN} = C_{IN} = 0V			1	mA
V_{REF}	Internal comparator (C_{IN}) reference voltage		0.51	0.54	0.56	V

Table 9. Bootstrapped voltage

Symbol	Parameter	Test condition	Min	Typ	Max	Unit
V_{BS_hys}	V_{BS} UV hysteresis		1.2	1.5	1.8	V
$V_{BS\_th(on)}$	V_{BS} UV turn-on threshold		11.1	11.5	12.1	V
$V_{BS\_th(off)}$	V_{BS} UV turn-off threshold		9.8	10	10.6	V
I_{QBSU}	Undervoltage V_{BS} quiescent current	V_{BS} < 9 V T/$\overline{SD}$/OD = 5 V; L_{IN} = 0 V; H_{IN} = 5 V; C_{IN} = 0 V;		70	110	µA
I_{QBS}	V_{BS} quiescent current	V_{BS} = 15 V T/$\overline{SD}$/OD = 5 V; L_{IN} = 0V;H_{IN} = 5V; C_{IN} = 0 V;		150	210	µA
$R_{DS(on)}$	Bootstrap driver on resistance	LVG ON		120		Ω

Table 10. Logic inputs

Symbol	Parameter	Test condition	Min	Typ	Max	Unit
V_{il}	Low logic level voltage				0.8	V
V_{ih}	High logic level voltage		2.25			V
I_{HINh}	HIN logic “1” input bias	HIN = 15V	20	40	100	µA
I_{HINl}	HIN logic “0” input bias current	HIN = 0V			1	µA
I_{LINh}	LIN logic “1” input bias current	LIN = 15V	20	40	100	µA
I_{LINl}	LIN logic “0” input bias current	LIN = 0V			1	µA
I_{SDh}	$\overline{SD}$ logic “0” input bias current	$\overline{SD}$ = 15V	220	295	370	µA
I_{SDl}	$\overline{SD}$ logic “1” input bias current	$\overline{SD}$ = 0V			3	µA
Dt	Dead time	See *Figure 8*		180		ns

Table 11. Op-amp characteristics

Symbol	Parameter	Test condition	Min	Typ	Max	Unit
V_{io}	Input offset voltage	V_{ic} = 0V, V_o = 7.5V			6	mV
I_{io}	Input offset current	V_{ic} = 0V, V_o = 7.5V		4	40	nA
I_{ib}	Input bias current(1)	V_{ic} = 0V, V_o = 7.5V		100	200	nA
V_{icm}	Input common mode voltage range		0			V
V_{OL}	Low level output voltage range	R_L = 10kΩ to V_{CC}		75	150	mV
V_{OH}	High level output voltage range	R_L = 10kΩ to GND	14	14.7		V
I_o	Output short-circuit current	Source V_{id} = +1V, V_o = 0V	16	30		mA
		Sink V_{id} = -1V, V_o = V_{CC}	50	80		mA
SR	Slew rate	V_i = 1-4V; C_L = 100pF; unity gain	2.5	3.8		V/µs
GBWP	Gain bandwidth product	V_o = 7.5V	8	12		MHz
A_{vd}	Large signal voltage gain	R_L = 2 kΩ	70	85		dB

Table 11. Op-amp characteristics (continued)

Symbol	Parameter	Test condition	Min	Typ	Max	Unit
SVR	Supply voltage rejection ratio	vs. V_{cc}	60	75		dB
CMRR	Common mode rejection ratio		55	70		dB

1. The direction of the input current is out of the IC.

Table 12. Sense comparator characteristics

Symbol	Parameter	Test condition	Min	Typ	Max	Unit
I_{ib}	Input bias current	V_{Cin} = 1V	-		3.1	µA
V_{od}	Open drain low level output voltage	I_{od} = 3mA	-		0.5	V
R_{ON_OD}	Open drain low level output resistance	I_{od} = 3mA	-	166		Ω
R_{PD_SD}	$\overline{SD}$ pull down resistor(1)		-	125		kΩ
t_{d_comp}	Comparator delay	T/$\overline{SD}$/OD pulled to 5V through 100 kΩ resistor	-	90	130	ns
SR	Slew rate	C_L = 180pF; R_{pu} = 5 kΩ	-	60		V/µs
t_{sd}	Shutdown to high/low side driver propagation delay	V_{OUT} = 0V, V_{boot} = V_{CC}, V_{IN} = 0 to 3.3V	-	125		ns
t_{isd}	Comparator triggering to high/low side driver turn-off propagation delay	Measured applying a voltage step from 0V to 3.3V to pin of C_{IN}	-	200		ns

1. Equivalent value as a result of the resistances of three drivers in parallel

Table 13. Truth table

Condition	Logic input (V_I)			Output	
	T/$\overline{SD}$/OD	LIN	HIN	LVG	HVG
Shutdown enable half-bridge tri-state	L	X(1)	X(1)	L	L
Interlocking half-bridge tri-state	H	H	H	L	L
0 “logic state” half-bridge tri-state	H	L	L	L	L
1 “logic state” Low side direct driving	H	H	L	H	L
1 “logic state” high side direct driving	H	L	H	L	H

1. X= don’t care.

3.1.1 NTC thermistor

Figure 4. Internal structure of $\overline{SD}$ and NTC(b)

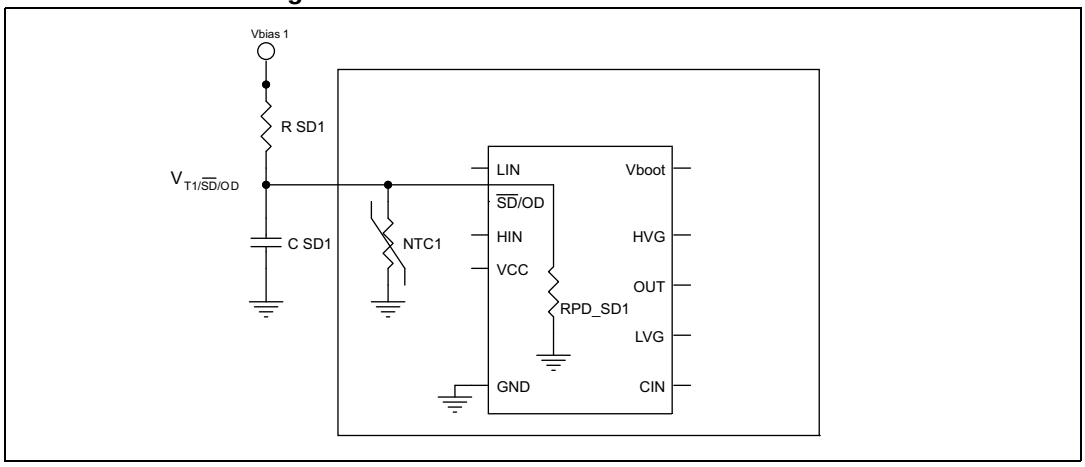
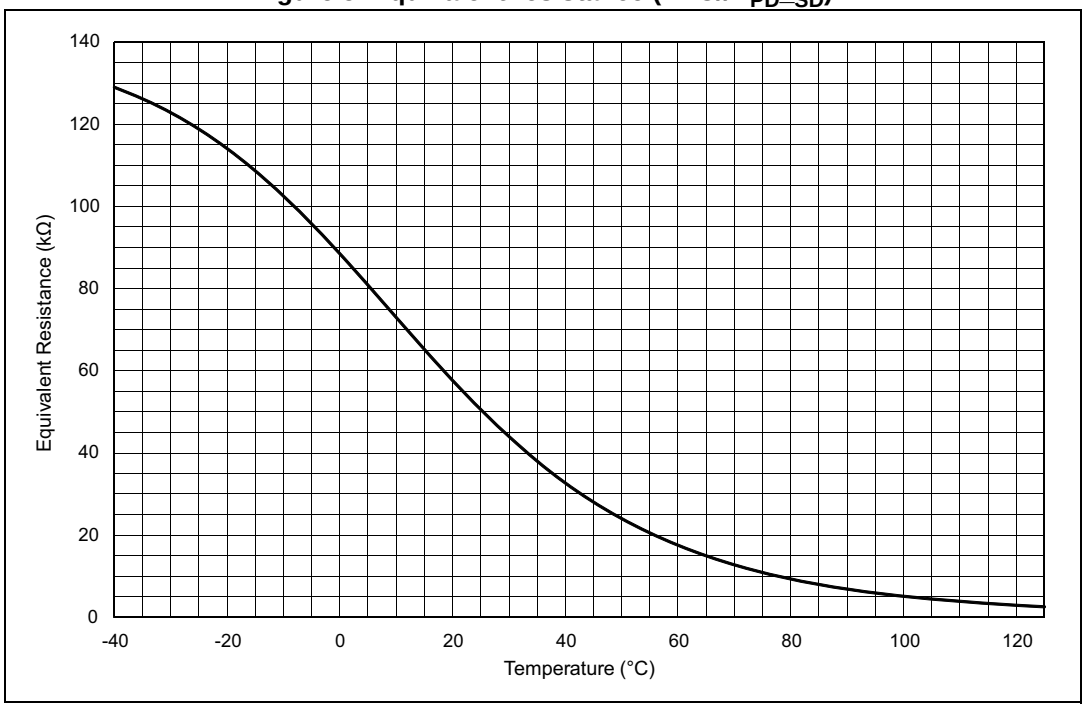


Figure 5. Equivalent resistance (NTC//R_{PD_SD})



b. RPD_SD: equivalent value as result of resistances of three drivers in parallel.

Figure 6. Equivalent resistance (NTC//R_{PD_SD}) zoom

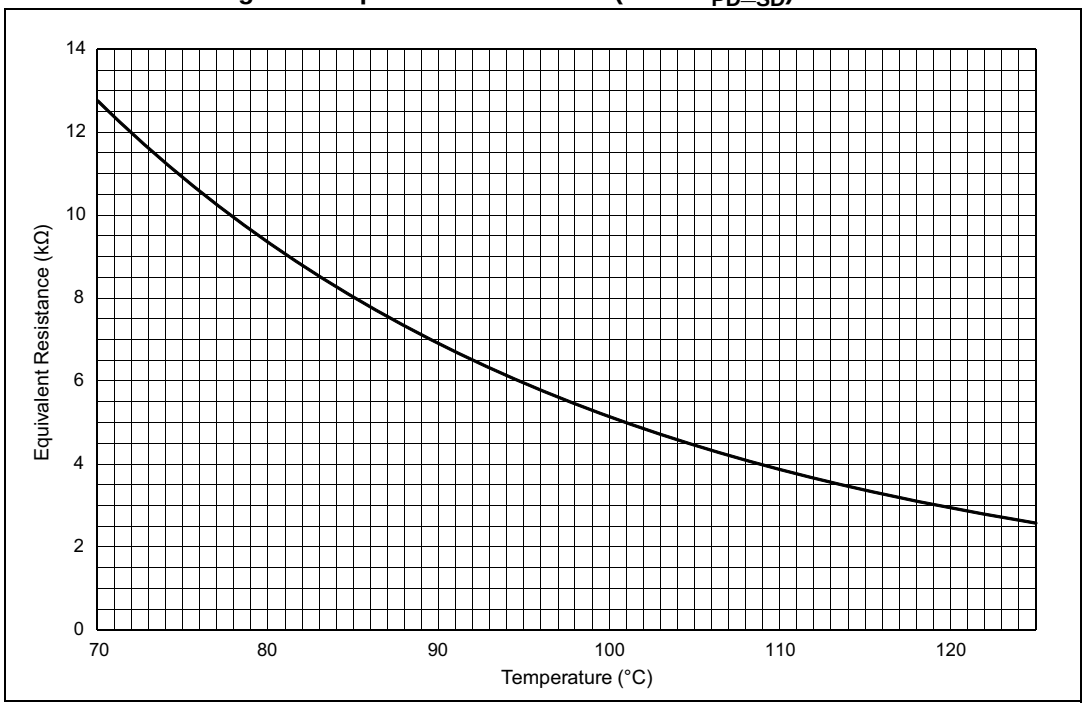
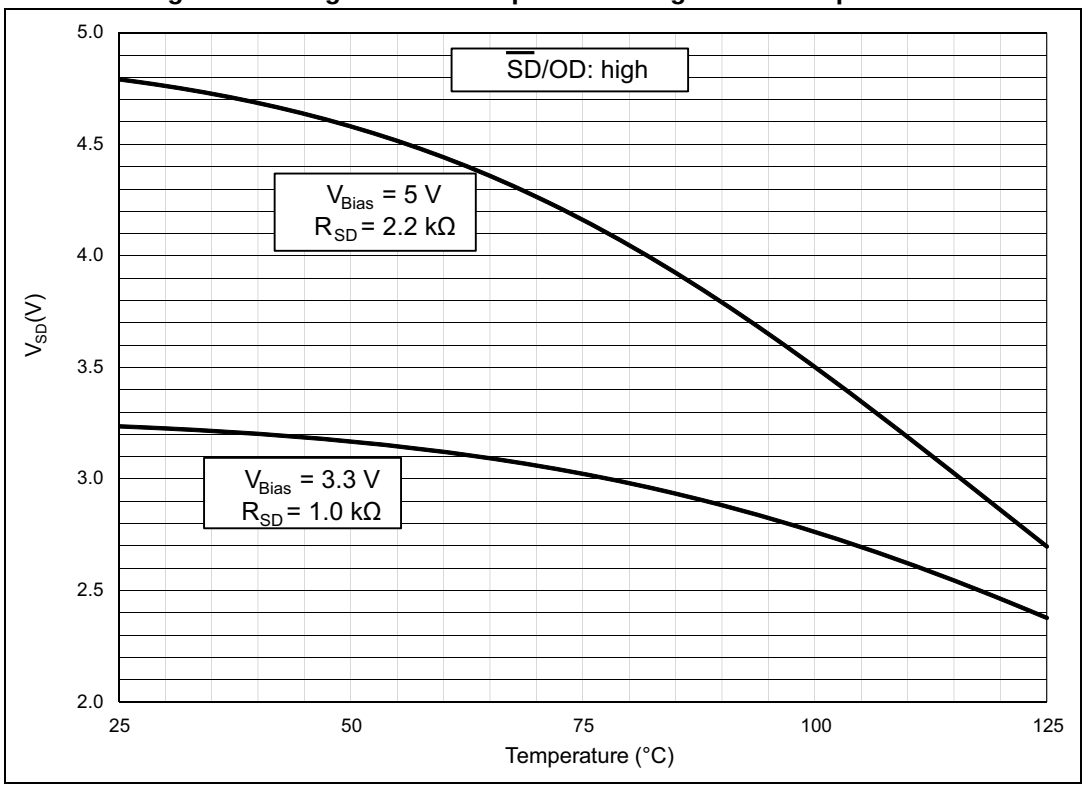
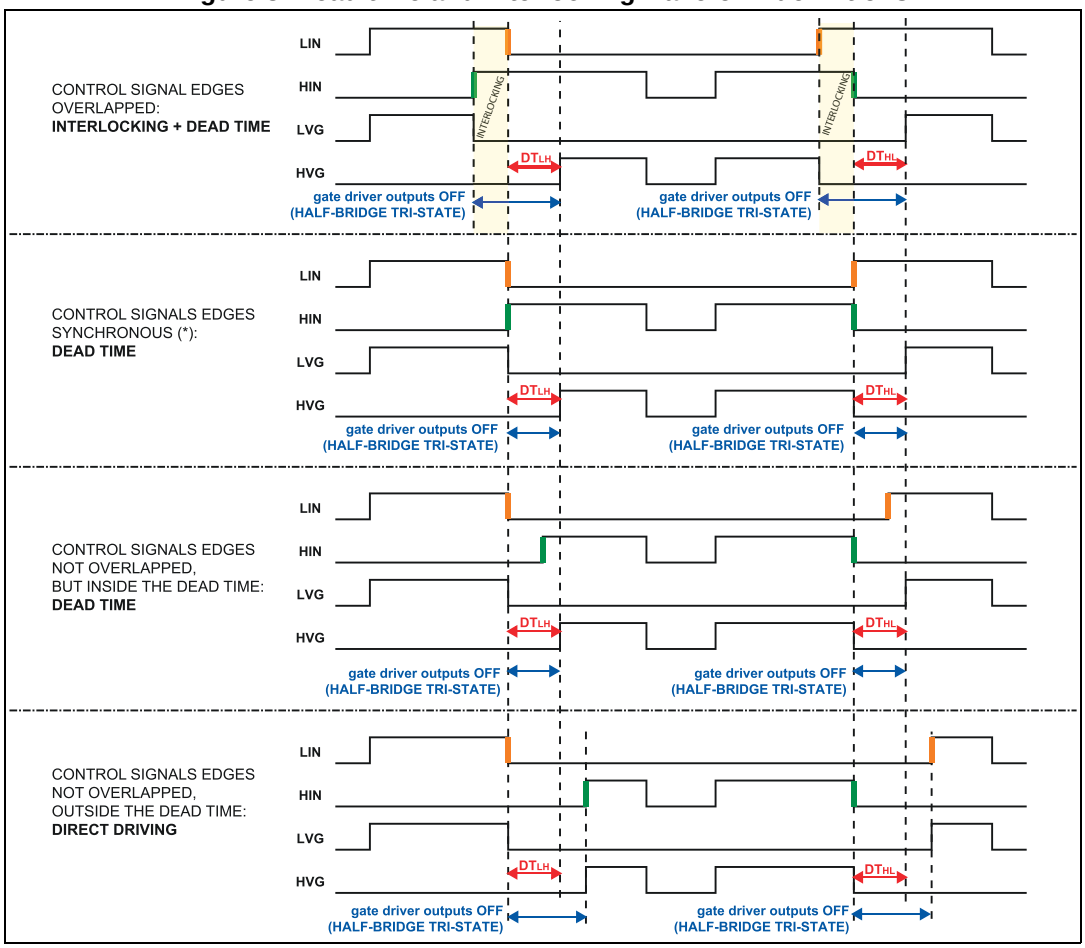


Figure 7. Voltage of T/$\overline{SD}$/OD pin according to NTC temperature



3.2 Waveforms definitions

Figure 8. Dead time and interlocking waveform definitions



4 Smart shutdown function

The device integrates a comparator for fault sensing purposes. The comparator has an internal voltage reference V_{REF} connected to the inverting input, while the non-inverting input on pin (CIN) can be connected to an external shunt resistor for simple overcurrent protection.

When the comparator triggers, the device is set to the Shutdown state and both its outputs are switched to the low-level setting, causing the half bridge to enter a tri-state.

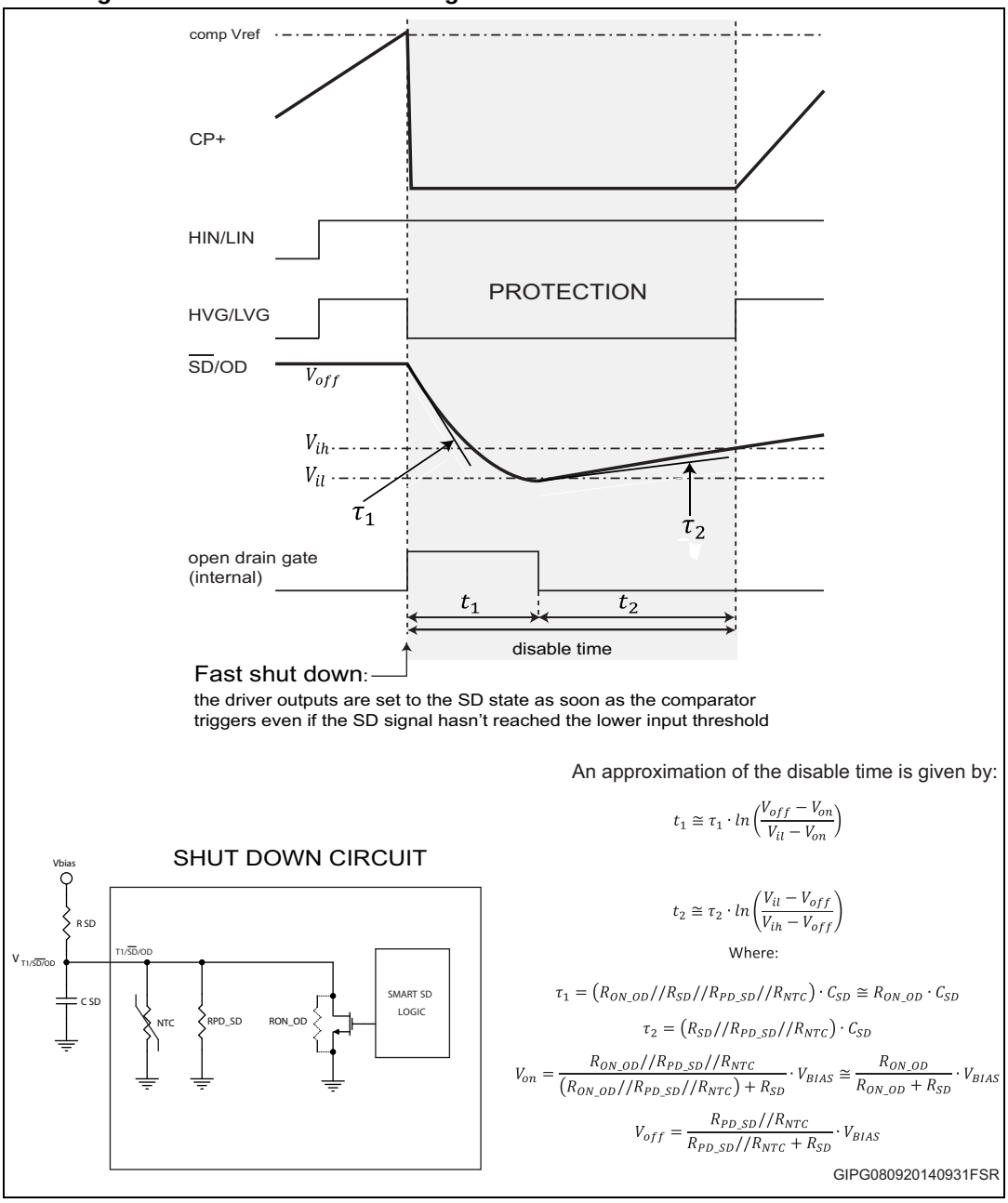
In common overcurrent protection architectures, the comparator output is usually connected to the Shutdown input through an RC network that provides a mono-stable circuit which implements a protection time following a fault condition.

Our smart shutdown architecture immediately turns off the output gate driver in case of overcurrent along a preferential path for the fault signal which directly switches off the outputs. The time delay between the fault and output shutdown no longer depends on the RC values of the external network connected to the shutdown pin. At the same time, the DMOS connected to the open-drain output (pin T/$\overline{SD}$/OD) is turned on by the internal logic, which holds it on until the shutdown voltage is lower than the logic input lower threshold (Vil).

Also, the smart shutdown function allows increasing the real disable time without increasing the constant time of the external RC network.

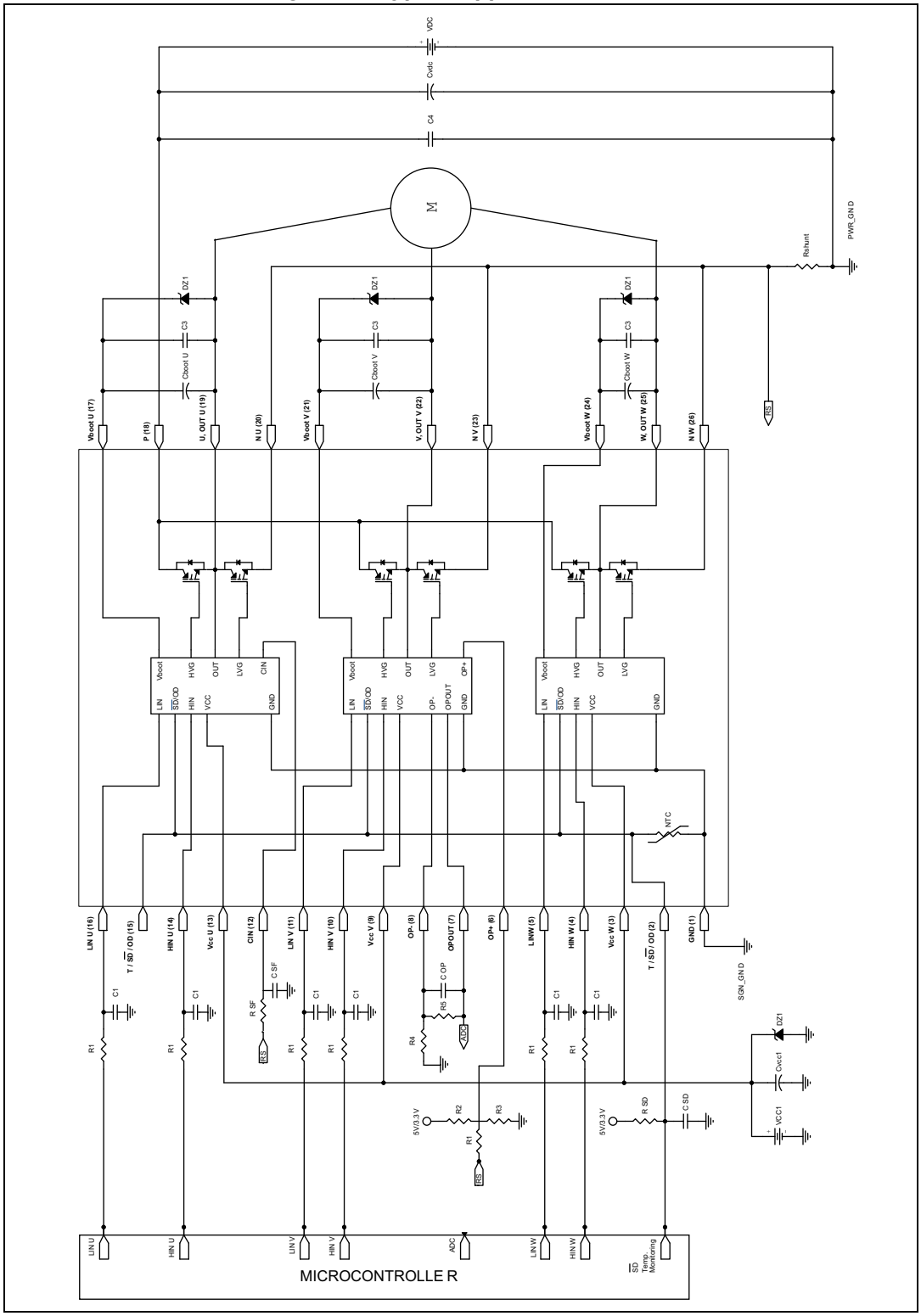
An NTC thermistor for temperature monitoring is internally connected in parallel to the $\overline{SD}$ pin. To avoid undesired shutdown, keep the voltage $V_{T/\overline{SD}/OD}$ higher than the high-level logic threshold by setting the pull-up resistor $R_{\overline{SD}}$ to 1 kΩ or 2.2 kΩ for the 3.3 V or 5 V MCU power supplies, respectively.

Figure 9. Smart shutdown timing waveforms in case of overcurrent event



5 Typical application circuit

Figure 10. Typical application circuit



6 Recommendations

- HIN and LIN are active-high logic input signals, each having an integrated 500 kΩ (typ.) pull-down resistor. Wire each input as short as possible and use RC filters (R1, C1) on each to prevent input signal oscillation. The filters should have a time constant of approximately 100 ns and must be placed as close as possible to the IPM input pins.
- Use a bypass capacitor Cvcc (aluminum or tantalum) to reduce the transient circuit demand on the power supply and a decoupling capacitor C2 (from 100 to 220 nF, ceramic with low ESR), placed as close as possible to each Vcc pin and in parallel to the bypass capacitor, to reduce high frequency switching noise distributed on the power supply lines.
- To prevent circuit malfunction, place an RC filter (RSF, CSF) with a time constant (RSF x CSF) of 1µs as close as possible to the CIN pin.
- The $\overline{SD}$ is an input/output pin (open drain type if used as output). An integrated NTC thermistor is connected internally between the $\overline{SD}$ pin and GND. The pull-up resistor RSD causes the voltage VSD-GND to decrease as the temperature increases. To always maintain the voltage above the high-level logic threshold, use a 1 kΩ or 2.2 kΩ pull-up resistor for a 3.3 V or 5 V MCU power supply, respectively. Size the filter on $\overline{SD}$ appropriately to obtain the desired re-start time after a fault event, and locate it as close as possible to the $\overline{SD}$ pin.
- Filter high-frequency disturbances by placing the decoupling capacitor C3 (from 100 to 220 nF, ceramic with low ESR) in parallel with each Cboot.
- Prevent overvoltage with Zener diodes DZ1 between the V_{CC} pins and GND and in parallel with each Cboot.
- Locate the decoupling capacitor C4 (from 100 to 220 nF, ceramic with low ESR) in parallel with the electrolytic capacitor Cvdc to prevent surge destruction. Place capacitors C4 (especially) and Cvdc as close as possible to the IPM.
- By integrating an application-specific type HVIC inside the module, direct coupling to the MCU terminals without an opto-coupler is possible.
- Use low inductance shunt resistors for phase leg current sensing.
- The wiring between N pins, the shunt resistor and PWR_GND should be as short as possible.
- Connect SGN_GND to PWR_GND at only one point (near the shunt resistor terminal), to avoid any malfunction due to power ground fluctuation.

Table 14. Recommended operating conditions

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
V_{PN}	Supply voltage	Applied between P-N_u,N_v,N_w		300	500	V
V_{CC}	Control supply voltage	Applied between V_{cc}-GND	13.5	15	18	V
V_{BS}	High side bias voltage	Applied between V_{bootx}-OUT for x = U,V,W	13		18	V
t_{dead}	Blanking time to prevent Arm-short	For each input signal	1.5			µs

Table 14. Recommended operating conditions (continued)

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
f_{PWM}	PWM input signal	-40°C<T_c<100°C -40°C<T_j<125°C			25	kHz
T_c	Case operation temperature				100	°C

7 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: *www.st.com*.
ECOPACK® is an ST trademark.

7.1 N2DIP-26L type L package information

Figure 11. N2DIP-26L type L package outline

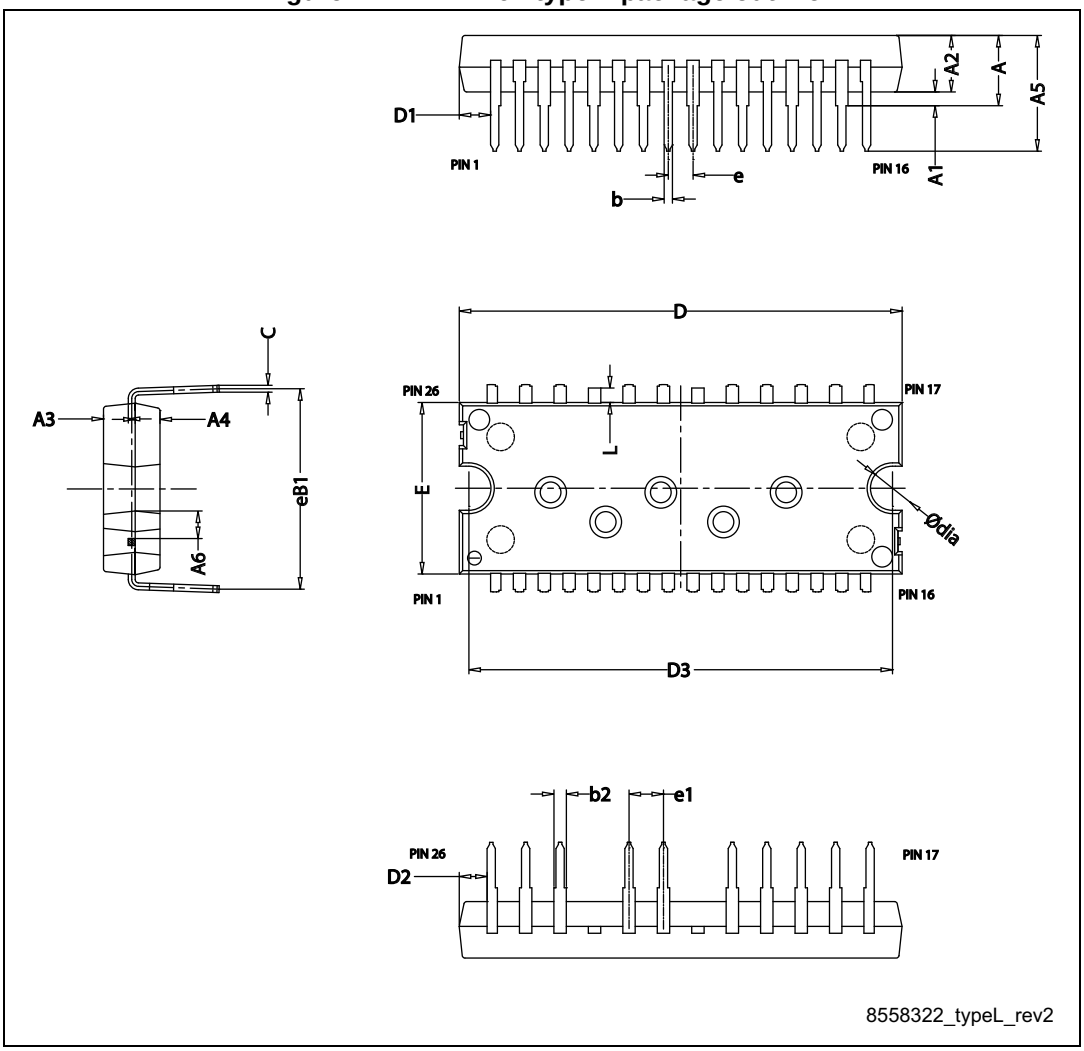


Table 15. N2DIP-26L type L package mechanical data(1)

Ref.	Dimensions			Ref.	Dimensions			Ref.	Dimensions		
	Min.	Typ.	Max.		Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.80	5.10	5.40	b	0.53		0.72	E	12.35	12.45	12.55
A1	0.80	1.00	1.20	b2	0.83		1.02	e	1.70	1.80	1.90
A2	4.00	4.10	4.20	c	0.46		0.59	e1	2.40	2.50	2.60
A3	1.70	1.80	1.90	D	32.05	32.15	32.25	eB1	14.25	14.55	14.85
A4	1.70	1.80	1.90	D1	2.10			L	0.85	1.05	1.25
A5	8.10	8.40	8.70	D2	1.85			dia	3.10	3.20	3.30
A6	1.75			D3	30.65	30.75	30.85				

1. All dimensions are expressed in millimeters.

7.2 N2DIP-26L type Z package information

Figure 12. N2DIP-26L type Z package outline

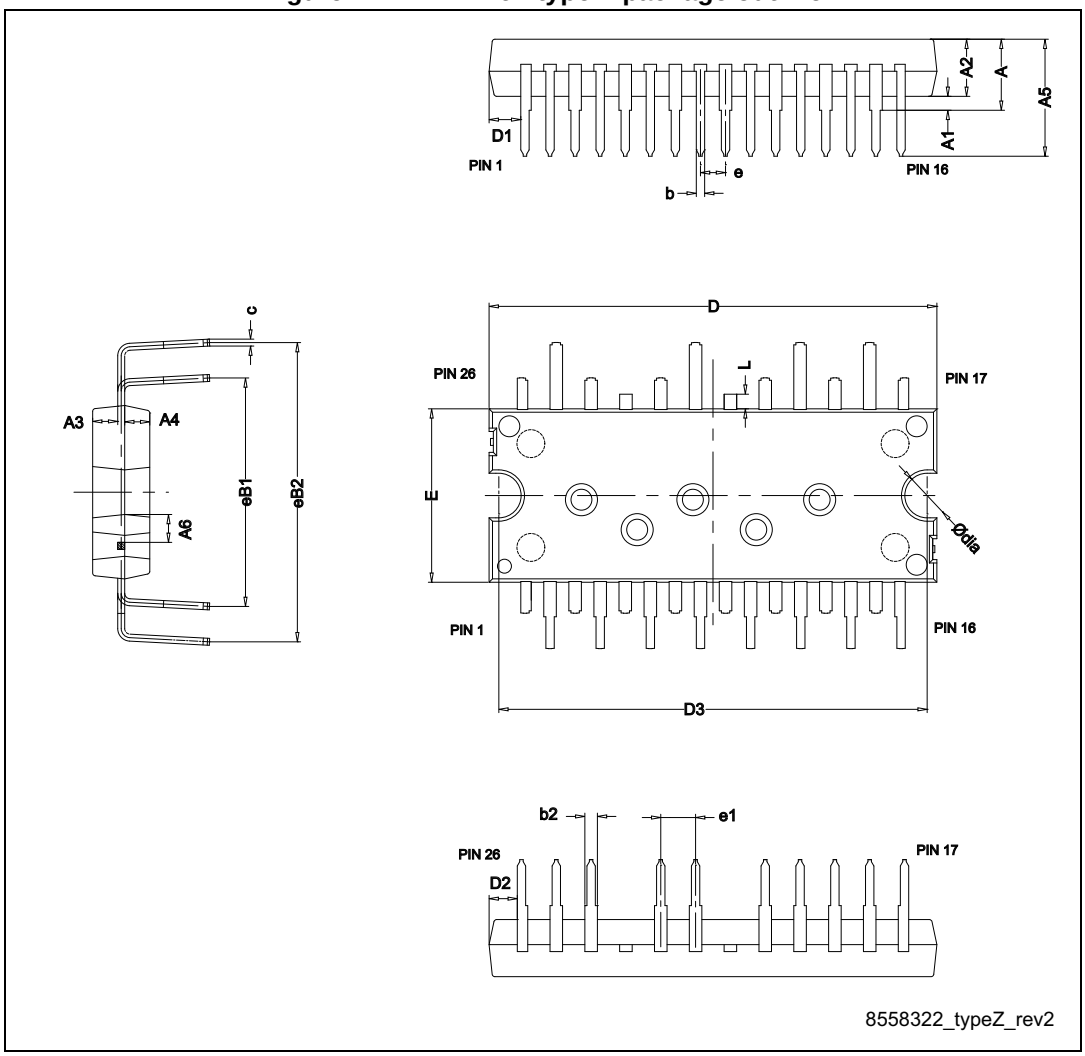


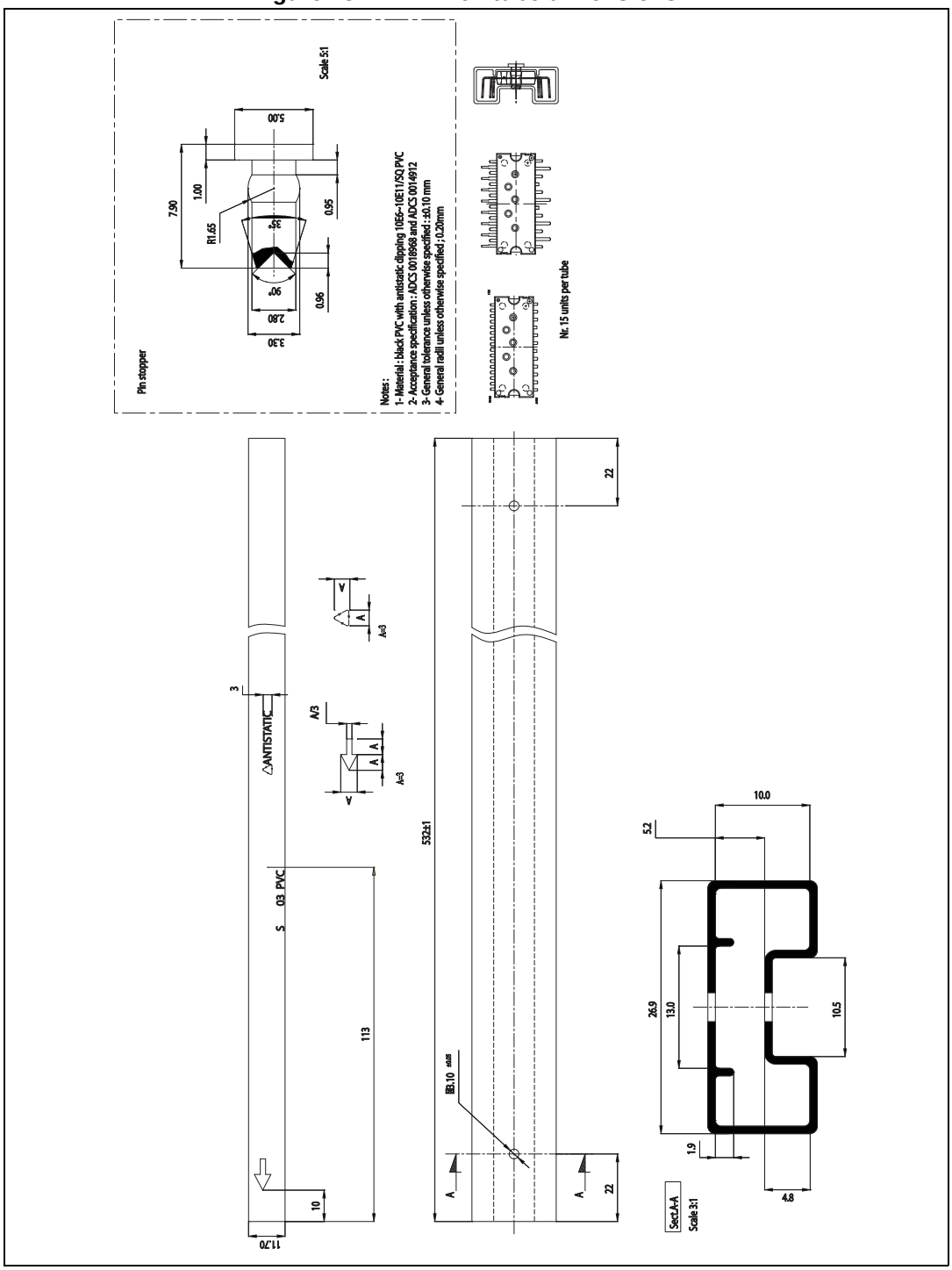
Table 16. N2DIP-26L type Z package mechanical data(1)

Ref.	Dimensions			Ref.	Dimensions			Ref.	Dimensions		
	Min.	Typ.	Max.		Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.80	5.10	5.40	b	0.53		0.72	E	12.35	12.45	12.55
A1	0.80	1.00	1.20	b2	0.83		1.02	e	1.70	1.80	1.90
A2	4.00	4.10	4.20	c	0.46		0.59	e1	2.40	2.50	2.60
A3	1.70	1.80	1.90	D	32.05	32.15	32.25	eB1	16.10	16.40	16.70
A4	1.70	1.80	1.90	D1	2.10			eB2	21.18	21.48	21.78
A5	8.10	8.40	8.70	D2	1.85			L	0.85	1.05	1.25
A6	1.75			D3	30.65	30.75	30.85	dia	3.10	3.20	3.30

1. All dimensions are expressed in millimeters.

7.3 Packing information

Figure 13. N2DIP-26L tube dimensions(c)



c. All dimensions are expressed in millimeters.

8 Revision history

Table 17. Document revision history

Date	Revision	Changes
25-Nov-2014	1	Initial release.
27-May-2015	2	Text and formatting changes throughout document On cover page: - updated *Features* - added N2DIP-26L type Z silhouette - renamed N2DIP-26L type L silhouette and package name (was N2DIP-26L) - renamed N2DIP-26L type Z package name (was N2DIP-26L) In *Section 2: Absolute maximum ratings*: - updated *Table 3: Inverter parts* In *Section 2.1: Thermal data*: - updated *Table 6: Thermal data* In *Section 3: Electrical characteristics*: - updated *Table 7: Inverter parts*
06-Jul-2015	3	Updated *Table 8: Low voltage power supply*, *Table 9: Bootstrapped voltage*, *Table 10: Logic inputs* and *Table 12: Sense comparator characteristics*. Minor text changes.
31-Jul-2015	4	Document status promoted from preliminary to production data.

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